

AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended) A method for manufacturing a flat printed wiring board, including the steps of:

_____ Obtaining a printed wiring board with a circuit pattern formed on a surface of the printed wiring board;

_____ forming a resin layer by superposing a semi-cured resin sheet on the surface of the a printed wiring board containing said with-circuit patterns, with complementary resin circuit patterns formed thereon on the semi-cured resin sheet;

_____ pressing and forcing the resin layer into spaces between said circuit patterns; and

_____ curing said resin layer; and then

_____ polishing said cured resin layer covering said circuit patterns, thereby exposing said circuit patterns,

wherein said semi-cured a-resin sheet with said complementary resin circuit patterns complementary to said circuit patterns are included on a surface of said semi-cured resin sheet facing said circuit patterns before said resin sheet is superposed on said printed wiring board.

Claim 2 (Currently Amended) A method for manufacturing a flat printed wiring board, including the following steps:

_____ forming a resin layer by superposing a semi-cured resin sheet on a printed wiring board where through holes and circuit patterns are formed;

_____ pressing and forcing the resin layer into spaces between said circuit patterns; and

_____ curing said resin layer; and then

_____ polishing the cured resin layer covering said circuit patterns, thereby exposing said circuit patterns;

wherein additional resin for filling said through holes is included at locations positions of said semi-cured resin sheet corresponding to said through holes before the resin sheet is superposed on said printed wiring board.

Claim 3 (Currently Amended) The method for manufacturing the flat a-printed wiring board according to claim 1 ~~or claim 2~~, wherein the pressing against said resin layer is performed in a reduced pressure atmosphere.

Claim 4 (Currently Amended) The method for manufacturing the flat a-printed wiring board according to ~~one of claim 1 to~~ claim 3 wherein a metallic foil with a roughened surface facing said resin layer is superposed and pressed on said resin layer.

Claim 5 (Currently Amended) The method for manufacturing the flat a-printed wiring board according to claim 4 wherein said metallic foil is formed with a metal of a different kind than said circuit patterns.

Claim 6 (New) The method for manufacturing the flat printed wiring board according to claim 5 wherein said metallic foil is formed from a nickel material.

Claim 7 (New) The method for manufacturing the flat printed wiring board according to claim 6 wherein said semi-cured resin sheets are formed from a thermosetting epoxy resin.

Claim 8 (New) The method for manufacturing the flat printed wiring board according to claim 6 wherein said semi-cured resin sheets are formed from a thermosetting resin.

Claim 9 (New) The method for manufacturing the flat printed wiring board according to claim 2 wherein the pressing against said resin layer is performed in a reduced pressure atmosphere.

Claim 10 (New) The method for manufacturing the flat printed wiring board according to claim 9 wherein a metallic foil with a roughened surface facing said resin layer is superposed and pressed on said resin layer.

Claim 11 (New) The method for manufacturing the flat printed wiring board according to claim 10 wherein said metallic foil is formed with a metal of a different kind than said circuit patterns.

Claim 12 (New) A method for manufacturing a flat printed wiring board, including the steps of:

forming a resin layer by superposing a semi-cured resin sheet on a printed wiring board where through holes and circuit patterns are formed;

pressing and forcing the resin layer into spaces between said circuit patterns and into said through holes;

curing said resin layer; and

polishing said cured resin layer, thereby exposing said circuit patterns,

wherein said semi-cured resin sheet includes complementary resin circuit patterns complementary to said circuit patterns on a surface of said semi-cured resin sheet facing said circuit patterns, and

wherein said semi-cured resin sheet further includes additional resin on said surface of said semi-cured resin sheet facing said circuit patterns at locations corresponding to positions of said through holes.

Claim 13 (New) The method for manufacturing the flat printed wiring board according to claim 12, wherein the step of pressing against said resin layer is performed in a reduced pressure atmosphere.

Claim 14 (New) The method for manufacturing the flat printed wiring board according to claim 13 wherein a metallic foil with a roughened surface facing said resin layer is superposed onto said resin layer prior to the step of pressing.

Claim 15 (New) The method for manufacturing the flat printed wiring board according to claim 14 wherein said metallic foil is formed with a metal of a different kind than said circuit patterns.

Claim 16 (New) The method for manufacturing the flat printed wiring board according to claim 15 wherein said metallic foil is formed from a nickel material.

Claim 17 (New) The method for manufacturing the flat printed wiring board according to claim 16 wherein said semi-cured resin sheets are formed from a thermosetting epoxy resin.

Claim 18 (New) The method for manufacturing the flat printed wiring board according to claim 16 wherein said semi-cured resin sheets are formed from a thermosetting resin.

Claim 19 (New) The method for manufacturing the flat printed wiring board according to claim 12 wherein said circuit patterns are formed by a subtractive method.

Claim 20 (New) The method for manufacturing the flat printed wiring board according to claim 1 wherein said circuit patterns are formed by a subtractive method.